


# MATERIAL DECLARATION SHEET



Material Number	P6SMB480A~550A, P6SMB130CA~550CA			
Product Line	Semiconductors			
Compliance Date	2015/04/08			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	4.479	Silicon	7440-21-3	60.1800%	2.898%	4.815%
				Phosphorous	7723-14-0	0.0100%	0.0005%	
				Boron	7440-42-8	0.0100%	0.0005%	
				Nickel	7440-02-0	14.8000%	0.713%	
				Lead Glass	7439-92-1	12.5000%	0.602%	
				Silicon dioxide	7631-86-9	10.0000%	0.482%	
				Aluminum oxide	1344-28-1	2.5000%	0.1204%	
2	High-melting point Solder paste	solder paste	3.02	Tin	7440-31-5	5.000%	0.162%	3.247%
				Lead	7439-92-1	92.500%	3.003%	
				Silver	7440-22-4	2.500%	0.081%	
3	Lead frame / Leads / Disc	Copper alloy	33.50	Copper	7440-50-8	99.800%	35.946%	36.018%
				Iron	7439-89-6	0.150%	0.054%	
				Phosphorus	7723-14-0	0.050%	0.018%	
4	Molding Compound	Epoxy material	51.00	Silica	14808-60-7	76.000%	41.673%	54.833%
				Epoxy resin	25928-94-3	9.000%	4.935%	
				Phenolic resin-A,-B	9003-35-4	8.000%	4.387%	
				Aluminum hydroxide	21645-51-2	6.000%	3.290%	
5	Plating	Matte-Tin	1.011	Carbon black	1333-86-4	1.000%	0.548%	1.087%
				Tin	7440-31-5	100.000%	1.087%	
Total Weight			93.01					

**This Document was updated on: 2015/04/08**

(EU) RoHS Directive 2011/65/EU ANNEX - Application of lead which are exempted from the requirements: 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) , and 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.